

F-mount package high power laser diode

Features:

- High reliability
- Au-Sn hard solder
- More compact
- High stability

Applications:

- Solid-state laser pumping
- Material processing
- Medical/Life and health sciences
- Illumination



Specifications (@25°C)	Symbol	Min	Typical	Max	Unit
Output Power	P _o	8.0			W
Operating Current	I _{op}		9.3	9.5	A
Operating Voltage	V _{op}		1.80	2.00	V
Threshold Current	I _{th}		1.8	2.0	A
Wavelength	λ	788	793	798	nm
Spectral Width (FWHM)	Δλ		3.0		nm
Wavelength Temperature Coeff.	Δλ/ΔT		0.3		nm/° C
Slope Efficiency	η	≥ 1.00	≥ 1.05		W/A
Power Conversion Efficiency	η _{TOT}		≥ 47		%
Parallel beam divergence	θ		8	10	Deg
Perpendicular beam divergence	θ _⊥	6.5	8	9.5	Deg
Maximum Reverse Voltage	V _{re}		≤ 2.5		V
Polarization			TE		
Mechanical					
Housing Dimension			See Drawing		
Lead Soldering Temp			260° C for <5 seconds		
Environmental					
Operating Temperature Range	T _{op}		15 to 25		° C
Operating Humidity	H _{op}		Non-condensing		RH
Storage Temperature Range	T _{STG}		-20 to 80		° C

*The F-mount test specifications are tested by CW driver mode at 25C.

Mechanical:

